



(0,80 mm) .0315"

HSEC8-130-01-L-D-EM2

DEC8-160-01-S

HSEC8-EM, DEC8 SERIES

EDGE MOUNT EDGE RATE™ CARD SOCKET

SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?HSEC8-EM

Insulator Material:

Liquid Crystal Polymer

Contact:

BeCu

Plating: Au or Sn over 50µ" (1,27 µm) Ni

Operating Temp:

-55°C to +125°C

Card Insertion Depth:

(3,15 mm) .125" nominal

Lead-Free Solderable: Yes

RoHS Compliant: Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE
(MOQ Required)

- Other platings
- Contact Samtec.

Note: While optimized for 50Ω applications, this connector with alternative signal/ground patterns may also perform well in certain 75Ω applications. Contact Samtec for further information.

Note: Requires PCB thickness of (1,60 mm) .062" ±(0,08 mm) .003"

HSEC8

1

POSITIONS
PER ROW

01

PLATING
OPTION

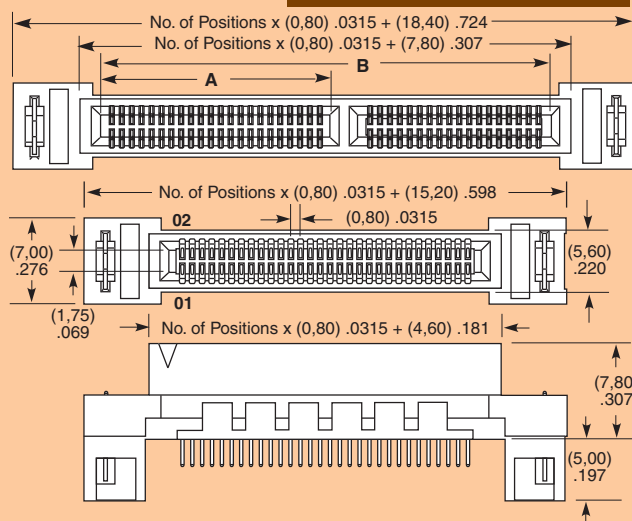
D

EM2

Mates with:

(1,60 mm) .062" thick cards,
ECDP, HSC8

10, 20, 30, 40, 50, 60



—L
= 10µ" (0,25 µm)
Gold on contact,
Matte Tin on tail

—S
= 30µ" (0,76 µm)
Gold on contact,
Matte Tin on tail

POS. PER ROW	A	B
40	(18,90) .744	(36,60) 1.441
50	(22,90) .902	(44,60) 1.756
60	(26,90) 1.059	(52,60) 2.071

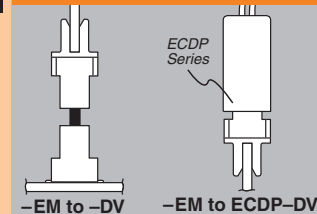
—EM2
= (1,60 mm) .062"
thick PCB

OTHER SOLUTIONS

Polarized mates for
ECDP Series twinax cables

CONNECTOR	CABLE
HSEC8-113	ECDP-08
HSEC8-125	ECDP-16
HSEC8-137	ECDP-24
HSEC8-149	ECDP-32

APPLICATIONS



SPECIFICATIONS

For complete specifications and recommended PCB layouts see www.samtec.com?DEC8

Insulator Material:

Black ABS

Contact:

BeCu

Plating: Au over 50µ" (1,27 µm) Ni

Operating Temp:

-55°C to +125°C

RoHS Compliant: Yes

RECOGNITIONS

For complete scope of recognitions see www.samtec.com/quality



ALSO AVAILABLE
(MOQ Required)

- Other platings
- Contact Samtec.

Note: Some lengths, styles and options are non-standard, non-returnable.

DEC8

1

POSITIONS
PER ROWLEAD
STYLE

PLATING

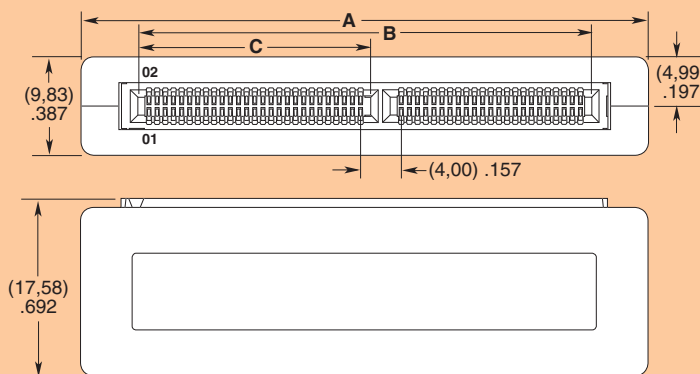
Mates with:

(1,60 mm) .062"
thick cards, HSC8

40, 50, 60

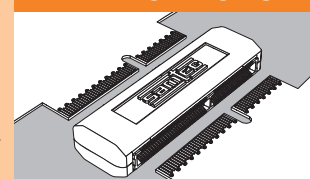
—01
= (1,60 mm) .062"
Card Thickness

—S
= 30µ" (0,76 µm)
Gold on contact



Moulding
removed for
clarity

APPLICATIONS



POSITIONS PER ROW	A	B	C
40	(47,75) 1.880	(36,60) 1.441	(18,90) .744
50	(55,75) 2.195	(44,60) 1.756	(22,91) .902
60	(63,75) 2.510	(52,60) 2.071	(26,90) 1.059

Due to technical progress, all designs, specifications and components are subject to change without notice.

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SAMTEC USA • Tel: +1-800-SAMTEC-9 or +1-812-944-6733 SAMTEC NORTHERN CALIFORNIA • Tel: +1-408-395-5900 SAMTEC SOUTHERN CALIFORNIA • Tel: +1-800-726-8329
SAMTEC SOUTH AMERICA • Tel: +55 31 3786 3227 SAMTEC UNITED KINGDOM • Tel: +44 01236 739292 SAMTEC GERMANY • Tel: +49 (0) 89 / 89460-0
SAMTEC FRANCE • Tel: +33 1 60 95 06 60 SAMTEC ITALY • Tel: +39 039 6890337 SAMTEC NORDIC/BALTIC • Tel: +46 8 4477280 SAMTEC BENELUX • Tel: +44 01236 739292
SAMTEC ISRAEL • Tel: +972 3 7526600 SAMTEC INDIA • Tel: +91 80 3272 1612 SAMTEC ANZ • Tel: +613 9580 0683 SAMTEC SINGAPORE • Tel: +65 6745 5955 SAMTEC JAPAN • Tel: +81 45 475 1385
SAMTEC SHANGHAI • Tel: +86 21 6083 3766 SAMTEC SHENZHEN • Tel: +86 755 83776780 SAMTEC TAIWAN • Tel: +886 2 2735 6109 SAMTEC HONG KONG • Tel: +852 26904658 SAMTEC KOREA • Tel: +82 31 717 5685